AGENDA

4th Panel Level Packaging Symposium
SEPTEMBER 8, 2022 | BERLIN

09:00 AM	**Arrival & Coffee**
09:30 AM	**Welcome** Rolf Aschenbrenner, Fraunhofer IZM
09:45 AM	**PLP Status – Joint Research Progress along the Process Chain** Dr. Tanja Braun, Fraunhofer IZM
10:30 AM	**Coffee Break**
10:45 AM	**A Hybrid Panel Platform Based on a 650mm Panel** Eoin OToole, AMKOR
11:15 AM	**Panel Level Assembly from Highest Speed to Highest Accuracy** Silvester Demmel, ASM
11:45 AM	**Lunch Break**
12:45 PM	**Development Of High-Density RDL Technologies for PLP** Lars Böttcher, Fraunhofer IZM
01:30 PM	**Advanced IC Substrate Technologies for PLP** Markus Leitgeb, AT&S
02:00 PM	**State of the Art Seed Layer Deposition on Panel Level and Carrier-less Thin Panel Handling in a Cluster-type Sputter Tool** Roland Rettenmeier, Evatec
02:30 PM	**Materials Strategies for High Density Packaging Applications** Sanjay Malik, FujiFilm
03:00 PM	**Coffee Break**
03:15 PM	**European Chips Act and Green Deal: challenges in the microelectronic industry** Mathilde Billaud, Fraunhofer IZM
03:45 PM	**Fan-Out Wafer and Panel Level Packaging Trends** Gabriela Pereira, Yole
04:15 PM	**Advanced Packaging: Challenges and Opportunities** Tarek Ibrahim, Intel
05:00 PM	**Lab Tour**
06:30 PM	**Evening Event: Yuna Berlin**